

DE2S062

Silicon epitaxial planar type

For ESD protection

■ Features

- High electrostatic discharge ESD
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 10000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Total power dissipation *1	P_T	150	mW
Electrostatic discharge *2	ESD	± 30	kV
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: $P_T = 150$ mW achieved with a printed circuit board.

*2: Test method: IEC61000-4-2 (C = 150 pF, R = 330 Ω , Contact discharge: 10 times)

■ Package

- Code
SSMini2-F5-B
- Pin Name
 1. Cathode
 2. Anode

■ Marking Symbol: E1

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

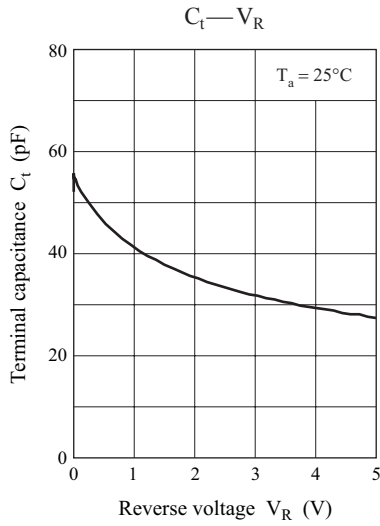
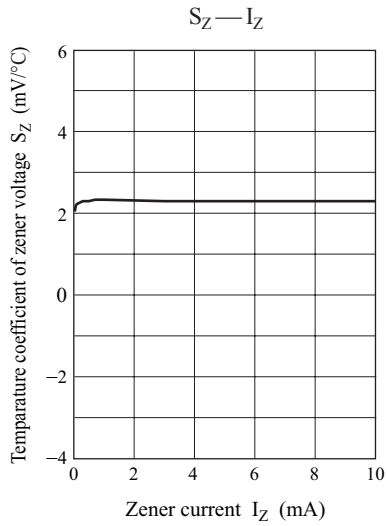
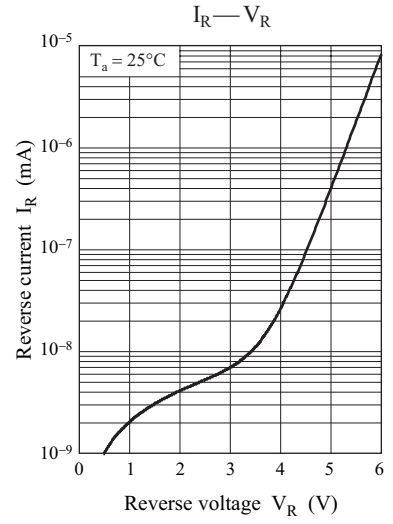
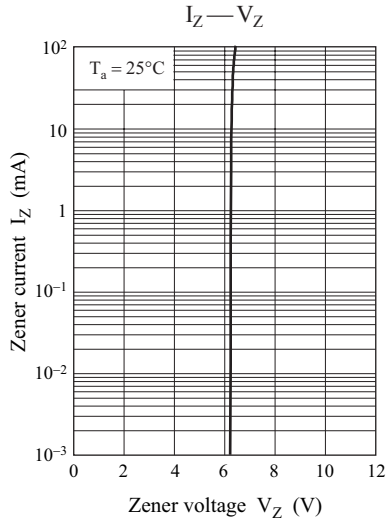
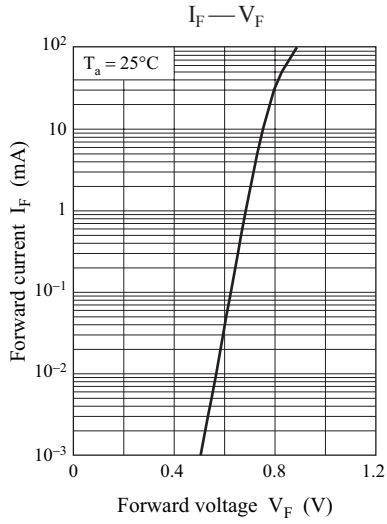
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage *1,2	V_Z	$I_R = 1$ mA	5.89		6.51	V
Reverse current	I_R	$V_R = 4$ V			1	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		55		pF
Temperature coefficient of zener voltage *3	S_Z	$I_Z = 1$ mA		2.3		mV/ $^\circ\text{C}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to $V_Z (25^\circ\text{C})$

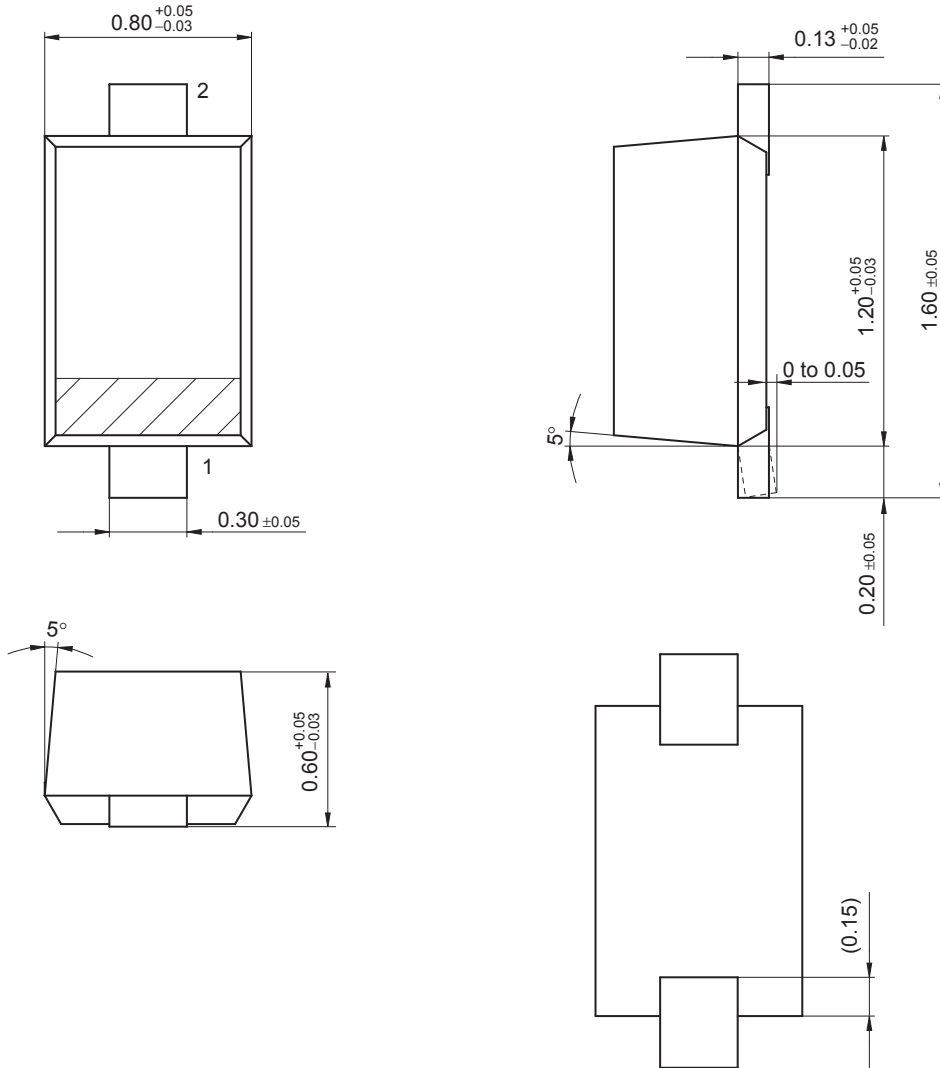
*2: V_Z guaranteed 20 ms after current flow.

*3: $T_j = 25^\circ\text{C}$ to 150°C



SSMini2-F5-B

Unit: mm



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